



LAYER STACKUP: (0.195" Total Board Thickness)

Top Layer: Top Trace (Copper Pour Ground)  
 Dielectric Thickness to get .195" board total thickness

Layer 2: Inner Power Plane  
 3 MIL Dielectric Thickness

Layer 3: Inner Ground Plane  
 Dielectric Thickness to get .195" board total thickness

Layer 4: Inner Ground Plane  
 Dielectric Thickness for 50 ohm impedance for inner trace 3 to Inner GND

Layer 5: Inner Trace 3 (50 ohm TTL Bussed Signals)  
 Dielectric Thickness for 50 ohm impedance for inner trace 3 to Bottom GND

Layer 6: Bottom Trace & GND (Copper Pour Ground)

DRILL CHART				
SYM	DIAM	TOL	QTY	NOTE
x	0.024		5062	
+	0.040		640	
◇	0.106		8	NON-PLATED
○	0.110		42	
TOTAL			5752	